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IME-01-012

U.S. Patent 5,879,572 to Folsom et al., "Method of Protecting Silicon Wafers During Wet Chemical Etching," discloses a bulk wet etch method.

U.S. Patent 5,338,416 to Mlcak et al., "Electrochemical Etching Process," discloses a method of photo-assisted electrochemical machining of micromechanical structure from a silicon substrate having both p and n regions in a hydrofluoric electrolyte solution.

U.S. Patent 6,025,278 to Rolfson, "Methods for Manufacturing Semiconductive Wafers and Semiconductive Material Stencil Masks," discloses a bulk wet etch process and apparatus in which the presence of etchant on the front side of the wafer is monitored and used to terminate etching once etch-through of via holes through the wafer has been achieved.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over a horizontal line.

Stephen B. Ackerman,
Reg. No. 37761

